

L Number	Hits	Search Text	DB	Time stamp
1	1240	implant\$7 and blister and substrate	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 13:24
3	116	(implant\$7 and blister and substrate) and calibrat\$4	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 12:00
4	1147	(implant\$7 and blister and substrate) and (dose or dosage)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 12:00
5	110	((implant\$7 and blister and substrate) and calibrat\$4) and ((implant\$7 and blister and substrate) and (dose or dosage))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 12:00
6	3280	implant\$7 and (blister or blistering or bubble) and substrate	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 12:00
7	348	(implant\$7 and (blister or blistering or bubble) and substrate) and calibrat\$4	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 12:00
8	2005	(implant\$7 and (blister or blistering or bubble) and substrate) and (dose or dosage)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 12:00
9	240	((implant\$7 and (blister or blistering or bubble) and substrate) and calibrat\$4) and ((implant\$7 and (blister or blistering or bubble) and substrate) and (dose or dosage))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 12:55
10	196	((((implant\$7 and (blister or blistering or bubble) and substrate) and calibrat\$4) and ((implant\$7 and (blister or blistering or bubble) and substrate) and (dose or dosage)))) and density	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 12:58
11	142	(((((implant\$7 and (blister or blistering or bubble) and substrate) and calibrat\$4) and ((implant\$7 and (blister or blistering or bubble) and substrate) and (dose or dosage)))) and density) and imag\$5	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 13:23
12	69	implant\$7 and blister and substrate and semiconductor	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:17
13	0	20020173872.URPN.	USPAT	2004/09/10 14:57

14	173	implant\$7 and blister and calibrat\$5	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:20
15	171	((implant\$7 and blister and calibrat\$5) not (implant\$7 and blister and substrate and semiconductor))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:20
16	0	((implant\$7 and blister and calibrat\$5) not (implant\$7 and blister and substrate and semiconductor)) and semiconductor	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:20
17	41	((implant\$7 and blister and calibrat\$5) not (implant\$7 and blister and substrate and semiconductor)) and silicon	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:20
18	380	implant\$7 and bubble and calibrat\$5	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:20
19	380	((implant\$7 and bubble and calibrat\$5) not (implant\$7 and blister and substrate and semiconductor))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:20
20	81	((implant\$7 and bubble and calibrat\$5) and semiconductor)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:20
22	13	((implant\$7 and bubble and calibrat\$5) and semiconductor) not ((implant\$7 and bubble and calibrat\$5) and silicon)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:21
21	142	((implant\$7 and bubble and calibrat\$5) and silicon)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:27
23	574	438/530	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:32
24	15	438/530 and (blister\$4 or bubbl\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:32

25	12	(438/530 and (blister\$4 or bubbl\$4)) not ((implant\$7 and bubble and calibrat\$5) and silicon) not ((implant\$7 and bubble and calibrat\$5) and semiconductor) not (((implant\$7 and blister and calibrat\$5) not (implant\$7 and blister and substrate and semiconductor))) and silicon) not (implant\$7 and blister and substrate and semiconductor)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:32
26	342	438/510	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:33
27	15	438/510 and (blister\$4 or bubbl\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:33
28	13	(438/510 and (blister\$4 or bubbl\$4)) not (438/530 and (blister\$4 or bubbl\$4)) not ((implant\$7 and bubble and calibrat\$5) and silicon) not ((implant\$7 and bubble and calibrat\$5) and semiconductor) not (((implant\$7 and blister and calibrat\$5) not (implant\$7 and blister and substrate and semiconductor))) and silicon) not (implant\$7 and blister and substrate and semiconductor)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:33
29	763	438/514	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:41
30	42	438/514 and (blister\$4 or bubbl\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:42
31	31	(438/514 and (blister\$4 or bubbl\$4)) not (438/510 and (blister\$4 or bubbl\$4)) not (438/530 and (blister\$4 or bubbl\$4)) not ((implant\$7 and bubble and calibrat\$5) and silicon) not ((implant\$7 and bubble and calibrat\$5) and semiconductor) not (((implant\$7 and blister and calibrat\$5) not (implant\$7 and blister and substrate and semiconductor))) and silicon) not (implant\$7 and blister and substrate and semiconductor)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:42
32	176	438/515	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:43
33	23	438/515 and (blister\$4 or bubbl\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:43

34	13	(438/515 and (blister\$4 or bubbl\$4)) not (438/514 and (blister\$4 or bubbl\$4)) not (438/510 and (blister\$4 or bubbl\$4)) not (438/530 and (blister\$4 or bubbl\$4)) not ((implant\$7 and bubble and calibrat\$5) and silicon) not ((implant\$7 and bubble and calibrat\$5) and semiconductor) not (((implant\$7 and blister and calibrat\$5) not (implant\$7 and blister and substrate and semiconductor)) and silicon) not (implant\$7 and blister and substrate and semiconductor)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:43
35	342	438/517	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:45
36	9	438/517 and (blister\$4 or bubbl\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:45
37	6	(438/517 and (blister\$4 or bubbl\$4)) not (438/515 and (blister\$4 or bubbl\$4)) not (438/514 and (blister\$4 or bubbl\$4)) not (438/510 and (blister\$4 or bubbl\$4)) not (438/530 and (blister\$4 or bubbl\$4)) not ((implant\$7 and bubble and calibrat\$5) and silicon) not ((implant\$7 and bubble and calibrat\$5) and semiconductor) not (((implant\$7 and blister and calibrat\$5) not (implant\$7 and blister and substrate and semiconductor)) and silicon) not (implant\$7 and blister and substrate and semiconductor)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:45
38	147	438/518	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:45
39	7	438/518 and (blister\$4 or bubbl\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:45
40	4	(438/518 and (blister\$4 or bubbl\$4)) not (438/517 and (blister\$4 or bubbl\$4)) not (438/515 and (blister\$4 or bubbl\$4)) not (438/514 and (blister\$4 or bubbl\$4)) not (438/510 and (blister\$4 or bubbl\$4)) not (438/530 and (blister\$4 or bubbl\$4)) not ((implant\$7 and bubble and calibrat\$5) and silicon) not ((implant\$7 and bubble and calibrat\$5) and semiconductor) not (((implant\$7 and blister and calibrat\$5) not (implant\$7 and blister and substrate and semiconductor)) and silicon) not (implant\$7 and blister and substrate and semiconductor)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:46
41	308	438/522	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:45
42	7	438/522 and (blister\$4 or bubbl\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:45

43	4	(438/522 and (blister\$4 or bubbl\$4)) not (438/518 and (blister\$4 or bubbl\$4)) not (438/517 and (blister\$4 or bubbl\$4)) not (438/515 and (blister\$4 or bubbl\$4)) not (438/514 and (blister\$4 or bubbl\$4)) not (438/510 and (blister\$4 or bubbl\$4)) not (438/530 and (blister\$4 or bubbl\$4)) not ((implant\$7 and bubble and calibrat\$5) and silicon) not ((implant\$7 and bubble and calibrat\$5) and semiconductor) not (((implant\$7 and blister and calibrat\$5) not (implant\$7 and blister and substrate and semiconductor)) and silicon) not (implant\$7 and blister and substrate and semiconductor)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:57
44	1958	438/\$5 and imaging and (ion or implant\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:49
45	157	(438/\$5 and imaging and (ion or implant\$4)) and (blister\$4 or bubbl\$5)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:49
46	155	((438/\$5 and imaging and (ion or implant\$4)) and (blister\$4 or bubbl\$5)) not (438/522 and (blister\$4 or bubbl\$4)) not (438/518 and (blister\$4 or bubbl\$4)) not (438/517 and (blister\$4 or bubbl\$4)) not (438/515 and (blister\$4 or bubbl\$4)) not (438/514 and (blister\$4 or bubbl\$4)) not (438/510 and (blister\$4 or bubbl\$4)) not (438/530 and (blister\$4 or bubbl\$4)) not ((implant\$7 and bubble and calibrat\$5) and silicon) not ((implant\$7 and bubble and calibrat\$5) and semiconductor) not (((implant\$7 and blister and calibrat\$5) not (implant\$7 and blister and substrate and semiconductor)) and silicon) not (implant\$7 and blister and substrate and semiconductor)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/09/10 15:57
47	0	20040152250.URPN.	USPAT	2004/09/10 16:13
48	3	6248661.URPN.	USPAT	2004/09/10 16:18
49	8	("4493855" "5223443" "5370969" "5394006" "5554567" "5694207" "5716673" "6121130").PN.	USPAT	2004/09/10 16:18